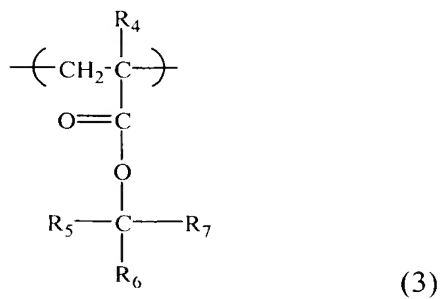
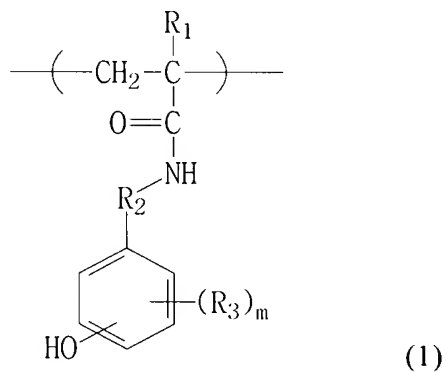


REMARKS

Claims 23-32 are pending. Favorable reconsideration is respectfully requested.

The present invention relates to a positive radiation-sensitive resin composition, comprising:

(A) a polymer containing structural units represented by formula (1), formula (3), and structural units obtained from p-isopropenylphenol,



wherein

R₁ is a hydrogen atom or a methyl group,

R₂ is $\text{---}(\text{CH}_2)_n\text{---}$,

n is an integer of 0 to 3, R₃ is an alkyl group of 1 to 4 carbon atoms,

m is an integer of 0 to 4,

R₄ is a hydrogen atom or a methyl group,

R₅ to R₇ are each an alkyl group of 1 to 4 carbon atoms, an alicyclic hydrocarbon group of 4 to 20 carbon atoms, an aromatic group or a substituted hydrocarbon group, wherein at least one hydrogen atom in any one of these hydrocarbon groups is replaced with a polar group other than a hydrocarbon group, wherein R₅ to R₇ may be the same or different, and when any two of R₅ to R₇ are alkyl groups or substituted alkyl groups, their alkyl chains may be bonded to each other to form an alicyclic hydrocarbon group of 4 to 20 carbon atoms or a substituted alicyclic hydrocarbon group;

(B) a component which generates an acid by irradiation with radiation; and

(C) an organic solvent.

See Claim 23.

The rejection of the claims under 35 U.S.C. §103(a) over Hamada et al. is respectfully traversed. Hamada et al. fail to disclose the claimed resin composition.

The composition disclosed in Hamada et al. has the structure corresponding to the formula (3) of the present application in order to improve resolution. However, the composition described in the reference does not have the structure corresponding to the formula (1) of the present application. Nor does the reference suggest such a component. As a result, the composition of Hamada et al. does not have good resolution and plating resistance compared to the composition of the present invention. This point is clearly shown by the comparison of Example 1-15, 15, and 22-23 with Comparative Examples.

In view of the foregoing, Hamada et al. fail to suggest the claimed composition. Accordingly, Claims 23-32 are not obvious over that reference. Withdrawal of this ground of rejection is respectfully requested.

The rejection of the claims under 35 U.S.C. §103(a) over Ohta et al. and Aoai et al. is respectfully traversed. The combination of Ohta et al. and Aoai et al. fails to suggest the claimed composition.

Aoai et al. disclose a composition having the structure corresponding to the formula (1) of the present invention, in particular N- (hydroxyphenyl) methacrylamide corresponding to the above formula (1) (column 35, line 47, and column 36, lines 52-53). However, the reference fails to disclose or suggest improving plating resistance. Moreover, N- (hydroxyphenyl) methacrylamide is an optional component which can be used within the range of not impairing transmissibility at 220 nm or less and dry etching resistance of the resin.

Ohta et al. disclose a composition having the structure corresponding to the formula (3) of the present application. However, this composition does not have good resolution and plating resistance compared to the composition of the present invention, because it does not contain the structure corresponding to formula (1). In the Examples of Ohta et al., the plating resistance is evaluated by the same procedure as that of the present invention and the good plated substrates were obtained without having a nodular abnormal protrusion. However, the composition of Ohta et al. does not contain a component corresponding to formula (3) of the present invention. As a result, the composition of Ohta et al. does not have good plating resistance and good shape of the bottom of the plated portion as shown by Comparative Examples 1-5 of the present invention.

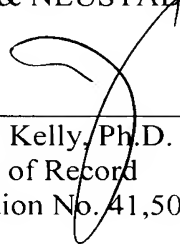
Thus, even if the composition of Ohta et al., which contains the component of formula (3) of the present invention (as does Hamada et al.), is combined with the composition of Aoai et al., which contains the component of formula (1) of the present invention, one skilled in the art would not obtain the claimed composition.

In view of the foregoing, the claimed composition is not suggested by the combination of Ohta et al. and Aoai et al. Accordingly, Claims 23-32 are not obvious over those references.

Applicants submit that the present application is in condition for allowance. Early notice to this effect is earnestly solicited.

Respectfully submitted,

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